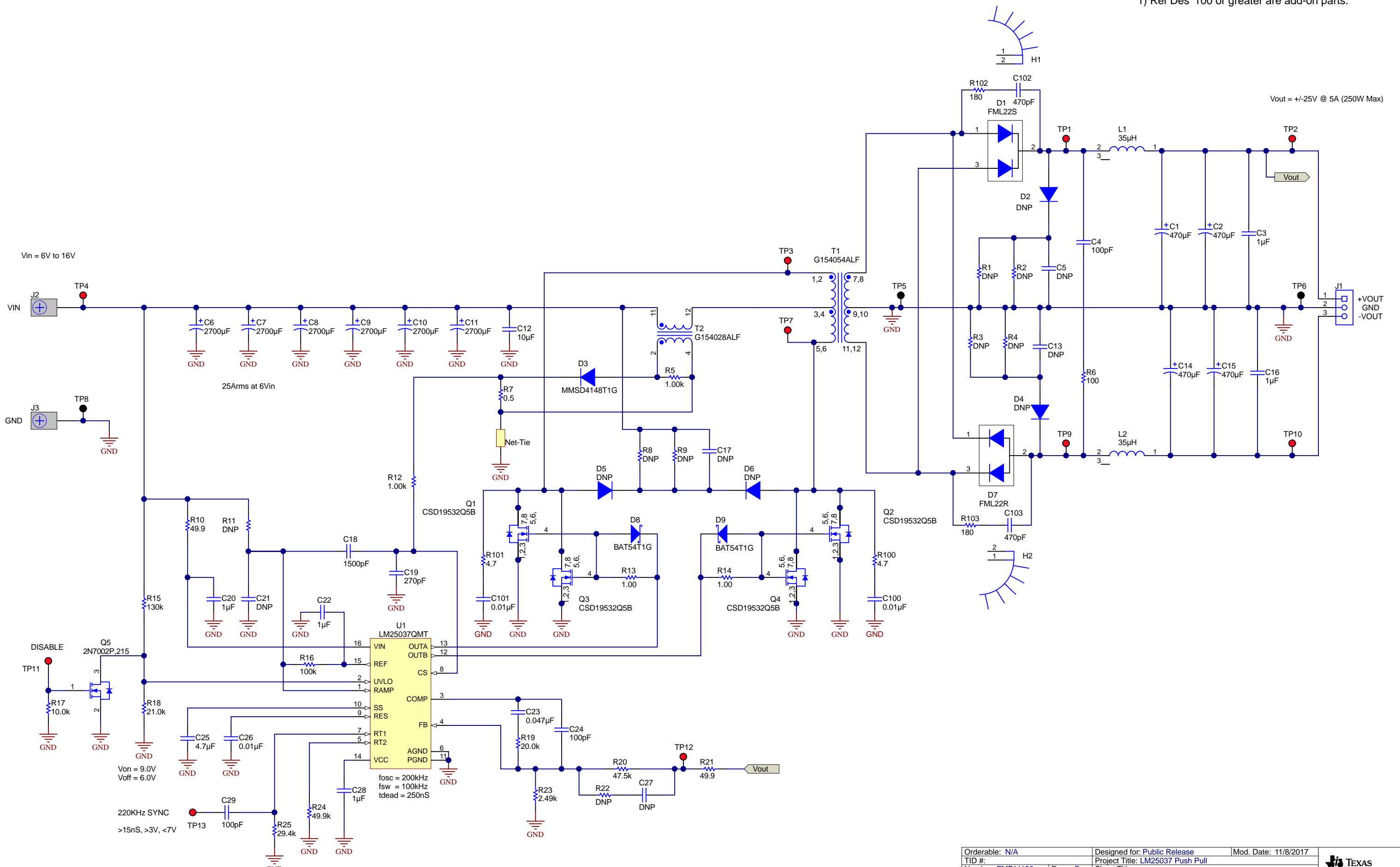


NOTES:  
1) Ref Des' 100 or greater are add-on parts.



Vin = 6V to 16V

25Arms at 6Vin

Vout = +/-25V @ 5A (250W Max)

Q5 2N7002P,215

U1 LM25037QMT

Von = 9.0V  
Voff = 6.0V

220kHz SYNC  
>15nS, >3V, <7V

fosc = 200kHz  
fsw = 100kHz  
tdead = 250nS

Orderable: N/A	Designed for: Public Release	Mod. Date: 11/8/2017
TID #:	Project Title: LM25037 Push Pull	
Number: PMP11186	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP11186 REV B.SchDoc	Size: B
Engineer: J Betten	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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